

Solid State Relay OCMOS FET

PS7214-1A

4-PIN SOP, 1.0 Ω LOW ON-STATE RESISTANCE 1-ch Optical Coupled MOS FET -NEPOC Series-

DESCRIPTION

The PS7214-1A is a low on-state resistance solid state relay containing a GaAs LED on the input side and MOS FETs on the output side.

It is suitable for PLC, etc. because of its large continuous load current and low on-state resistance.

FEATURES

- Low on-state resistance ($R_{on} = 1.0 \Omega TYP$.)
- Large continuous load current (I_L = 400 mA)
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- High isolation voltage (BV = 1 500 Vr.m.s.)
- Low offset voltage
- Ordering number of taping product : PS7214-1A-E3, E4: 900 pcs/reel
 - : PS7214-1A-F3, F4: 3 500 pcs/reel
- <R> Pb-Free product
- <R> Safety standards
 - UL approved: File No. E72422
 - BSI approved: No. 8241/8242

APPLICATIONS

- Measurement equipment
- FA equipment

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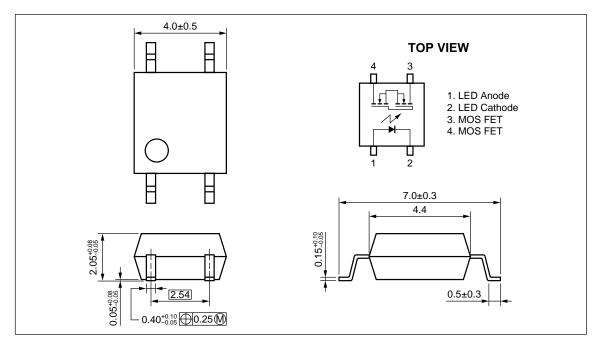
Document No. PN10298EJ02V0DS (2nd edition) Date Published August 2006 NS CP(K)

The mark <R> shows major revised points.

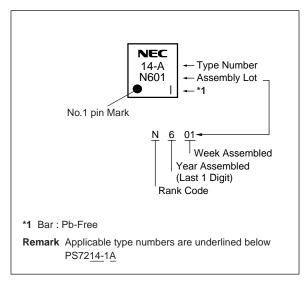
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The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

PACKAGE DIMENSIONS (Unit: mm)



<R> MARKING EXAMPLE (LASER MARKING)



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS7214-1A	PS7214-1A-A	Pb-Free	Magazine case 100 pcs	Standard products	PS7214-1A
PS7214-1A-E3	PS7214-1A-E3-A		Embossed Tape 900 pcs/reel	(UL, BSI	
PS7214-1A-E4	PS7214-1A-E4-A			approved)	
PS7214-1A-F3	PS7214-1A-F3-A		Embossed Tape 3 500 pcs/reel		
PS7214-1A-F4	PS7214-1A-F4-A				

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Diode Forward Current (DC)		50	mA
	Reverse Voltage	VR	5.0	V
	Power Dissipation	PD	50	mW
	Peak Forward Current ^{*1}	IFP	1	А
MOS FET	Break Down Voltage	VL	100	V
	Continuous Load Current	١L	400	mA
	Pulse Load Current ^{*2} (AC/DC Connection)	Ilp	0.8	A
Power Dissipation		PD	300	mW
Isolation Voltage ^{*3}		BV	1 500	Vr.m.s.
Total Power Dissipation		Ρτ	350	mW
Operating Ambient Temperature		TA	-40 to +85	°C
Storage Temperature		Tstg	-40 to +100	°C

***1** PW = 100 μs, Duty Cycle = 1%

*2 PW = 100 ms, 1 shot

*3 AC voltage for 1 minute at $T_A = 25^{\circ}$ C, RH = 60% between input and output Pins 1-2 shorted together, 3-4 shorted together.

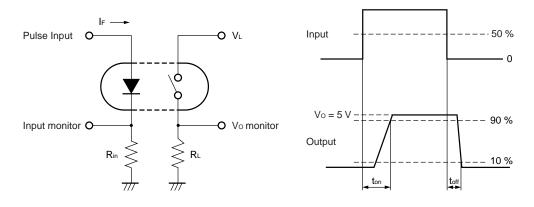
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lf	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

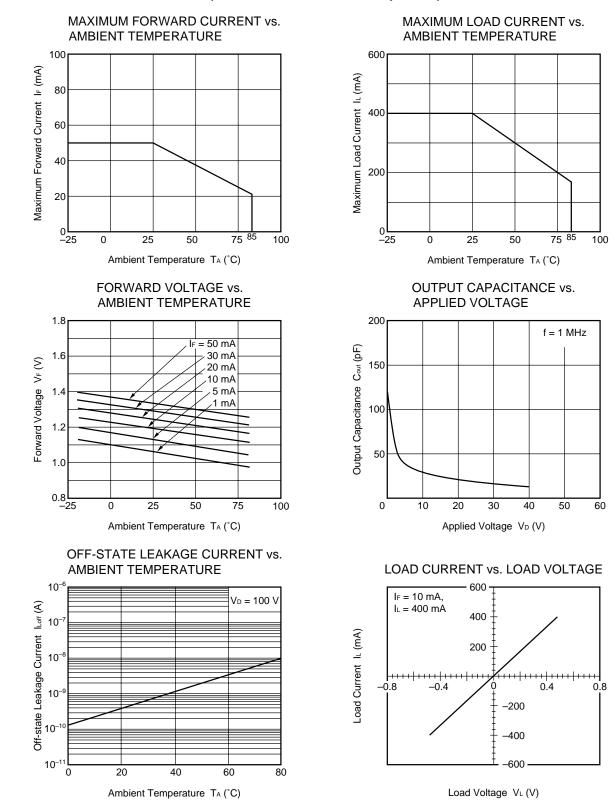
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	IR	V _R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	Loff	V _D = 100 V			1.0	μA
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		120		pF
Coupled	LED On-state Current	IFon	I∟ = 400 mA			2.0	mA
	On-state Resistance	Ron	I_{F} = 10 mA, I_{L} = 400 mA, $t \leq$ 10 ms		1.0	1.2	Ω
	Turn-on Time ^{*1, 2}	ton	I_{F} = 10 mA, Vo = 5 V, RL = 500 Ω ,		1.3	2.0	ms
	Turn-off Time ^{*1, 2}	toff	$PW \ge 10 ms$		0.1	1.0	
	Isolation Resistance	Ri-o	VI-O = 1.0 kVDC	10 ⁹			Ω
	Isolation Capacitance	CI-0	V = 0 V, f = 1 MHz		0.5		pF

*1 Test Circuit for Switching Time



<R> *2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms. Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

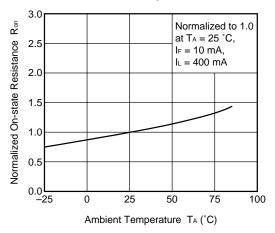


TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

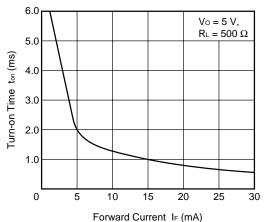
Remark The graphs indicate nominal characteristics.

Data Sheet PN10298EJ02V0DS

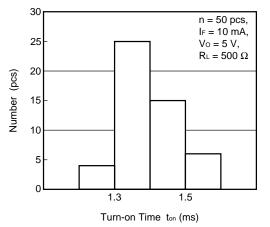
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



TURN-ON TIME vs. FORWARD CURRENT

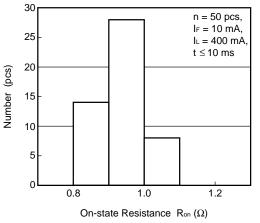


TURN-ON TIME DISTRIBUTION

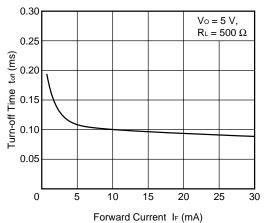


Remark The graphs indicate nominal characteristics.

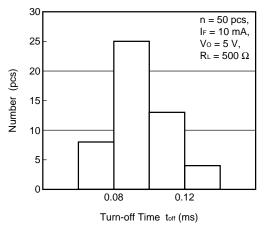
ON-STATE RESISTANCE DISTRIBUTION

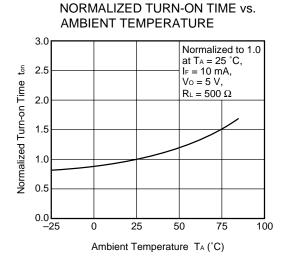


TURN-OFF TIME vs. FORWARD CURRENT

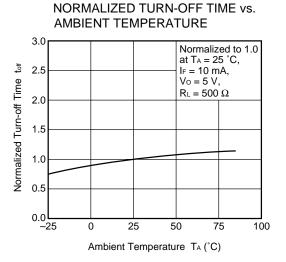


TURN-OFF TIME DISTRIBUTION

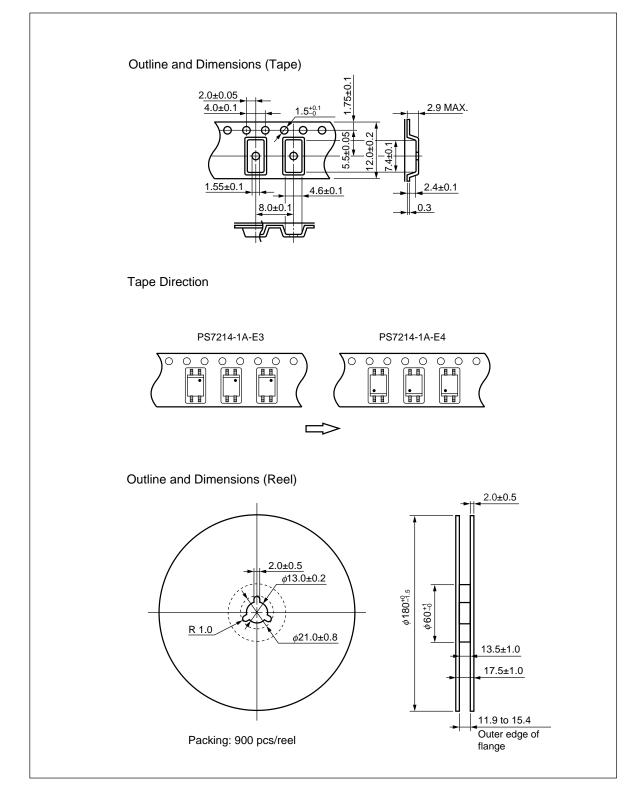




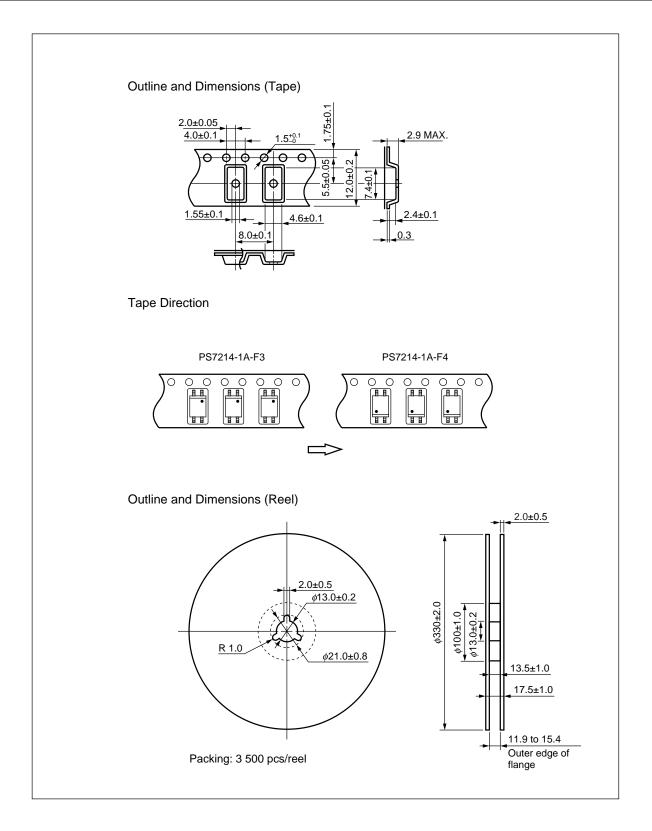
Remark The graphs indicate nominal characteristics.



TAPING SPECIFICATIONS (in millimeters)



Data Sheet PN10298EJ02V0DS



Data Sheet PN10298EJ02V0DS

RECOMMENDED SOLDERING CONDITIONS

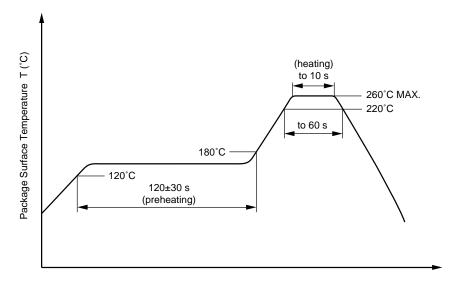
(1) Infrared reflow soldering

- Peak reflow temperature
- Time of peak reflow temperature
- Time of temperature higher than 220°C
- Time to preheat temperature from 120 to 180°C
- Number of reflows
- Flux

260°C or below (package surface temperature) 10 seconds or less 60 seconds or less 120±30 s Three Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

 Temperature 	260°C or below (molten solder temperature)
• Time	10 seconds or less
 Preheating conditions 	120°C or below (package surface temperature)
 Number of times 	One
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

<R> (3) Soldering by soldering iron

 Peak temperature (lead part temperature) 	350°C or below
 Time (each pins) 	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a
	maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> USAGE CAUTIONS

- **1.** Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.
	• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	 Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
	Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
	• Do not burn, destroy, cut, crush, or chemically dissolve the product.
	• Do not lick the product or in any way allow it to enter the mouth.

NEC Compound Semiconductor Devices Hong Kong Limited E-mail: contact@ncsd-hk.necel.com Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309 Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859 Korea Branch Office TEL: +82-2-558-2120 FAX: +82-2-558-5209 NEC Electronics (Europe) GmbH http://www.eu.necel.com/ TEL: +49-211-6503-0 FAX: +49-211-6503-1327 California Eastern Laboratories, Inc. http://www.cel.com/ TEL: +1-408-988-3500 FAX: +1-408-988-0279 **Compound Semiconductor Devices Division NEC Electronics Corporation**

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